

Inductors

RF chokes, LBC series

Series/Type: B82144F

Date: June 2012

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LBC series, 6.5 x 9.2 (mm)

Datasheet

LBC chokes, axial leaded Rated inductance 1 ... 100000 μH Rated current 20 ... 2500 mA

Construction

- Large ferrite drum core
- Winding: enamel copper wire
- Flame-retardant lacquer coating

Features

- Very wide inductance range
- High rated current
- Suitable for wave soldering
- RoHS-compatible

Applications

- RF blocking and filtering
- Decoupling and interference suppression
- For telecommunications, automotive electronics, energy-saving lamps, entertainment electronics

Terminals

- Central axial lead
- Base material CuAg0.1
- Electroplated with nickel and pure tin

Marking

■ Inductance indicated by color bands in accordance with IEC 60062

Delivery mode and packing unit

- Taped, reel packing
- Packing unit:

	Ammo	Reel	
	(pcs./pack)	(pcs./reel)	
B82144F	1200	1500	

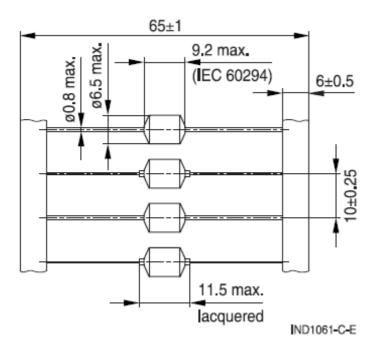




LBC series, 6.5 x 9.2 (mm)

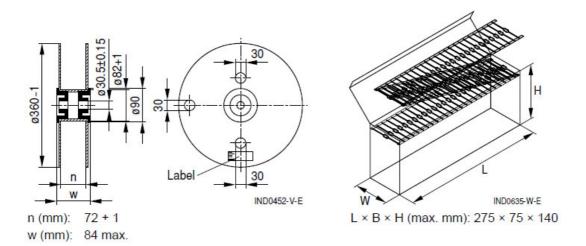
Datasheet

Dimensional drawing



Dimensions in mm

Packing



Dimensions in mm



LBC series, 6.5 x 9.2 (mm)

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Technical data and measuring conditions

Rated inductance L _R	Measured with LCR meter Agilent 4284A or impedance analyzer Agilent 4294A Measuring frequency: $L_R \le 10~\mu\text{H}$ = 1 MHz $10~\mu\text{H} < L_R \le 4700\mu\text{H}$ = 100 kHz $L_R > 4700\mu\text{H}$ = 10 kHz Measuring current: $\le 1~\text{mA}$ Measuring temperature: +20 °C						
Q factor Q _{min}	Measured with precision impedance analyzer Agilent 4294A, +20 °C						
Rated temperature T _R	+40 °C						
Rated current I _R	Maximum permissible DC current at rated temperature						
Inductance decrease ΔL/L ₀	≤ 10% (referred to initial value) at I _R , +20 °C						
DC resistance R _{max}	Measured at +20 °C						
Resonance frequency f _{res,min}	Measured with Agilent 4294A or 8753ES, +20 °C						
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (+3 ±0.3) s Wetting of soldering area ≥ 90% (to IEC 60068-2-20, test Ta)						
Resistance to soldering heat	(+260 ±5)°C, +10 s (to IEC 60068-2-20. test Tb)						
Tensile strength of leads	≥ 20 N (to IEC 60068-2-21. test Ua)						
Climatic category	55/125/56 (to IEC 60068-1)						
Storage conditions	Mounted: -55 °C +125 °C Packaged: -25 °C +40 °C, ≤ 75% RH						
Weight	Approx. 0.95 g						



Mounting information

When bending the leads, take care that the start-of-winding areas at the face ends (protected by glue and lacquer) are not subjected to any mechanical stress.



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Characteristics and ordering codes

L _R [µH]	Tolerance ¹⁾	Q _{min}	f _Q [MHz]	I _R [mA]	R _{max} [Ω]	f _{res,min} [MHz]	Ordering code ²⁾
1.0	±10% ≙ K	25	7.96	2500	0.06	200	B82144F1102K000
1.5		25	7.96	2300	0.07	180	B82144F1152K000
2.2		25	7.96	2100	0.09	140	B82144F1222K000
3.3		25	7.96	1950	0.10	120	B82144F1332K000
4.7		25	7.96	1800	0.12	100	B82144F1472K000
6.8		25	7.96	1600	0.15	60	B82144F1682K000
10		60	2.52	1500	0.18	24	B82144F1103K000
15		60	2.52	1400	0.22	17	B82144F1153K000
22		50	2.52	1250	0.28	12	B82144F1223K000
33	± 5% ≙ J	40	2.52	1100	0.35	8.0	B82144F1333J000
47		40	2.52	900	0.41	7.0	B82144F1473J000
56		40	2.52	850	0.47	7.0	B82144F1563J000
68		30	2.52	800	0.52	6.2	B82144F1683J000
100		40	0.796	760	0.70	5.2	B82144F1104J000
150		40	0.796	670	0.90	4.5	B82144F1154J000
220		40	0.796	550	1.30	3.8	B82144F1224J000
330		30	0.796	500	1.70	3.2	B82144F1334J000
470		30	0.796	400	2.20	2.9	B82144F1474J000
680		20	0.796	340	3.10	2.6	B82144F1684J000
820		20	0.796	310	3.70	2.4	B82144F1824J000
1000		60	0.252	280	4.20	2.2	B82144F1105J000
1500		60	0.252	230	6.40	1.9	B82144F1155J000
2200		60	0.252	180	9.50	1.5	B82144F1225J000
3300		60	0.252	150	13.8	1.3	B82144F1335J000
4700		60	0.252	120	21.0	1.1	B82144F1475J000
5600		60	0.252	110	28.0	1.0	B82144F1565J000
6800		60	0.252	100	30.0	0.9	B82144F1685J000
10000		50	0.0796	85	42.0	0.75	B82144F1106J000
15000		50	0.0796	50	75.0	0.50	B82144F1156J000
22000		50	0.0796	40	120	0.40	B82144F1226J000
33000		50	0.0796	35	150	0.30	B82144F1336J000
47000		40	0.0796	30	230	0.26	B82144F1476J000
68000		40	0.0796	25	290	0.20	B82144F1686J000
100000		40	0.0796	20	490	0.18	B82144F1107J000

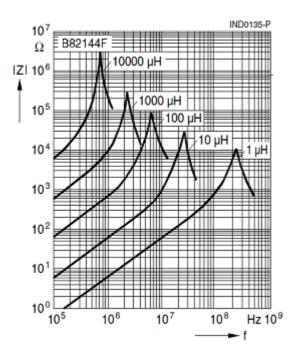
¹⁾ Closer tolerance on request. ²⁾ For Ammo pack the last digit has to be a "9". Example: B82144F1223K009



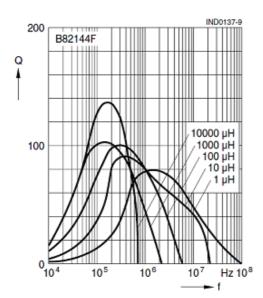
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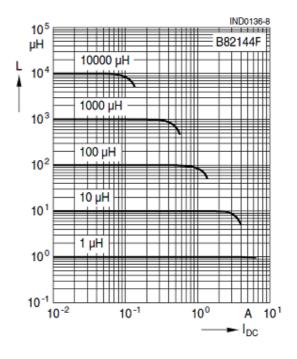
Impedance |**Z**| versus frequency f measured with impedance analyzer Agilent 4294A or S-parameter network analyzer Agilent 8753ES, typical values at +20°C



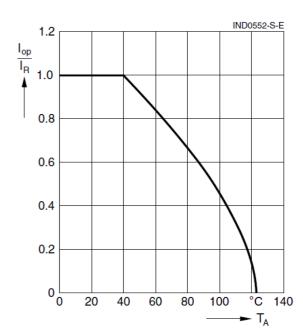
Q factor versus frequency f measured with impedance analyzer Agilent 4294A, typical values at +20°C



Inductance L versus DC load current I_{DC} measured with LCR meter Agilent 4284A, typical values at +20°C



Current derating I_{OP}/I_R versus ambient temperature T_A (rated temperature $T_R = +40$ °C)





Cautions and warnings

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation
 Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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